

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20230306001.1 Datasheet for OPAx277 Change Notification

Date:March 08, 2023To:PREMIER FARNELLPCN

Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

Data Sheet Change Notification Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE

OPA2277UA OPA2277UA/2K5E4

CUSTOMER PART NUMBER

null null

Technical details of this Product Change follow on the next page(s).

PCI	N Number:	202	303060	001	.1	PCN Dat	te:	Marc	h 08, 2023	
Titl	e: Datasheet for	OPAx	277							
Customer Contact: PCN Manager						Dept:		Quality Services		
Pro	posed 1 st Ship Date	e:	June	8, 2	023					
	ange Type:									
	Assembly Site				Design			Wafer	- Bump Site	
	Assembly Process		\boxtimes	Data Sheet			Wafer Bump Material			
	Assembly Materials			Part number change			Wafer Bump Process			
	Mechanical Specification			Test Site			Wafer	- Fab Site		
Packing/Shipping/Labeling			Test Process			Wafer	- Fab Materials			
					- ·			Wafer Fab Process		
Notification Details										
Des	cription of Change	:								
	as Instruments Inco product datasheet(Texas INSTRUMENTS					d below.		OPA	277, OPA2277, OPA4277 19 – REVISED FEBRUARY 2023	
c	hanges from Revision	B (Anr	·il 2015)	tol	Revision C (February	(2023)			Page	
	 Changed Offset Trim pin type from "Input" to "—"									
De OP The	a datasheet number vice Family Ax277 ese changes may be p://www.ti.com/proc	reviev	wed at	the	Change From: SBOS079B	provided.			ge To: 5079C	
Reason for Change:										
То	To accurately reflect device characteristics.									

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Electrical specification performance changes as indicated above.

Changes to product identification resulting from this PCN:

None. Product Affected:								
OPA2277AIDRMTG4	OPA2277UA/2K5E4	OPA277PAG4	OPA277UG4					
OPA2277P	OPA2277UAE4	OPA277U	OPA4277PA					
OPA2277PA	OPA2277UAG4	OPA277U/2K5	OPA4277UA					
OPA2277PAG4	OPA2277UG4	OPA277U/2K5G4	OPA4277UA/2K5					
OPA2277U	OPA277AIDRMR	OPA277UA	OPA4277UA/2K5E4					
OPA2277U/2K5	OPA277AIDRMT	OPA277UA/2K5	OPA4277UAE4					
OPA2277U/2K5G4	OPA277AIDRMTG4	OPA277UA/2K5E4	OPA4277UAG4					
OPA2277UA	OPA277P	OPA277UAE4						

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail				
WW PCN Team	PCN ww admin team@list.ti.com				

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